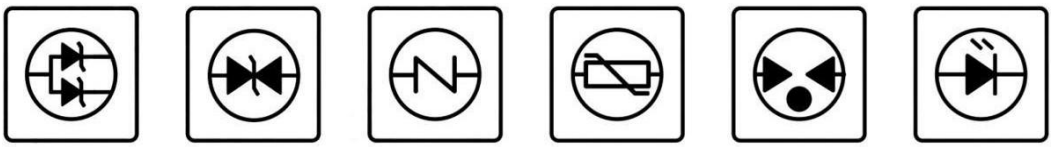
MSKSEMI 美森科
SEMICONDUCTOR



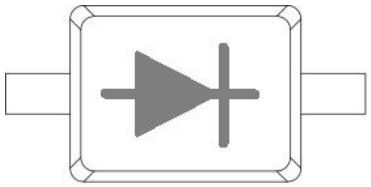
BAT54WS

Product specification

FEATURES

- Extremely Fast Switching Speed
- Low Forward Voltage

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		
SOD-323		

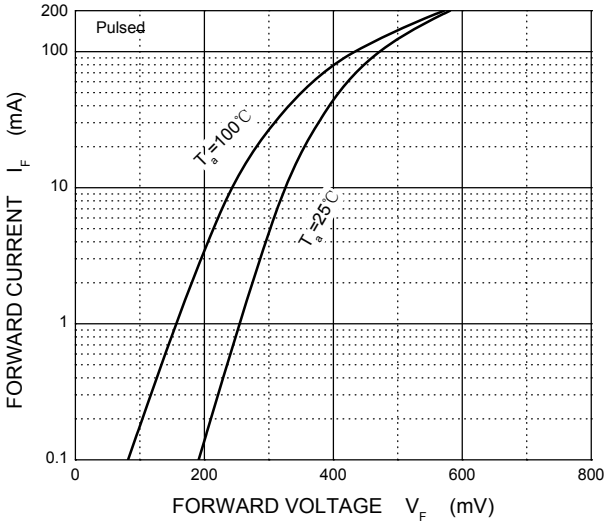
Maximum Ratings @Ta=25℃

Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	30	V
DC Blocking Voltage	V_R	21	V
Average Rectified Output Current	I_O	100	mA
Forward Continuous Current	I_F	200	mA
Repetitive Peak Forward Current	I_{FRM}	300	mA
Non-repetitive Peak Forward Surge Current @t=8.3ms	I_{FSM}	600	mA
Power Dissipation	P_D	200	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	500	℃/W
Operating Junction Temperature Range	T_J	-40 ~ +125	℃
Storage Temperature Range	T_{STG}	-55 ~ +150	℃

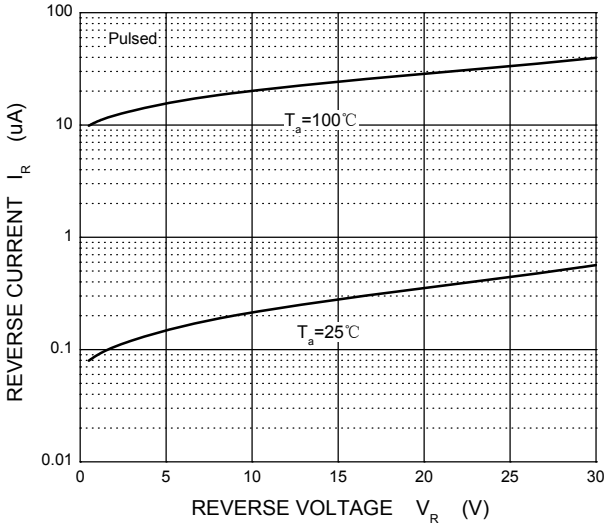
Electrical Characteristics @Ta=25℃

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse breakdown voltage	$V_{(BR)}$	I_R=100μA	30			V
Forward voltage	V_{F1}	I_F=0.1mA			240	mV
	V_{F2}	I_F=1.0mA			320	mV
	V_{F3}	I_F=10mA			400	mV
	V_{F4}	I_F=30mA			500	mV
	V_{F5}	I_F=100mA			1000	mV
Reverse current	I_R	V_R=25V			2.0	uA
Reverse recovery time	t_{rr}	I_F=10mA, I_R=10mAto 1mA , R_L=100Ω			5.0	ns
Capacitance between terminals	C_T	V_R=1V,f=1MHz			10	pF

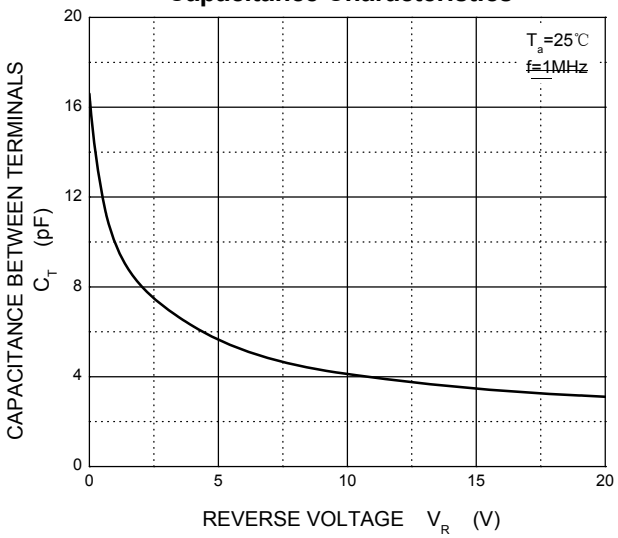
Forward Characteristics



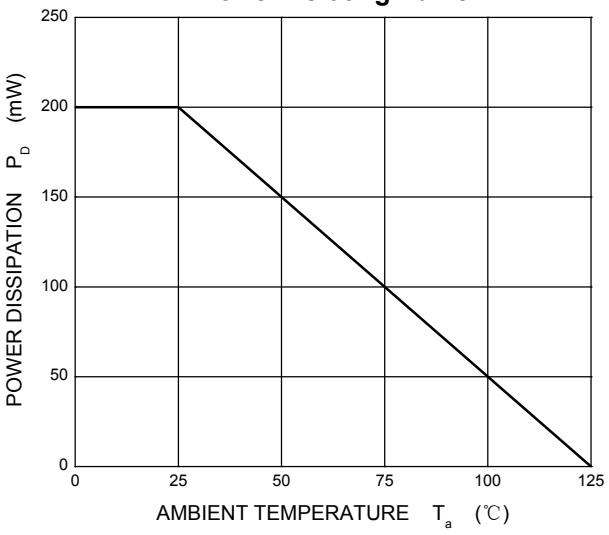
Reverse Characteristics



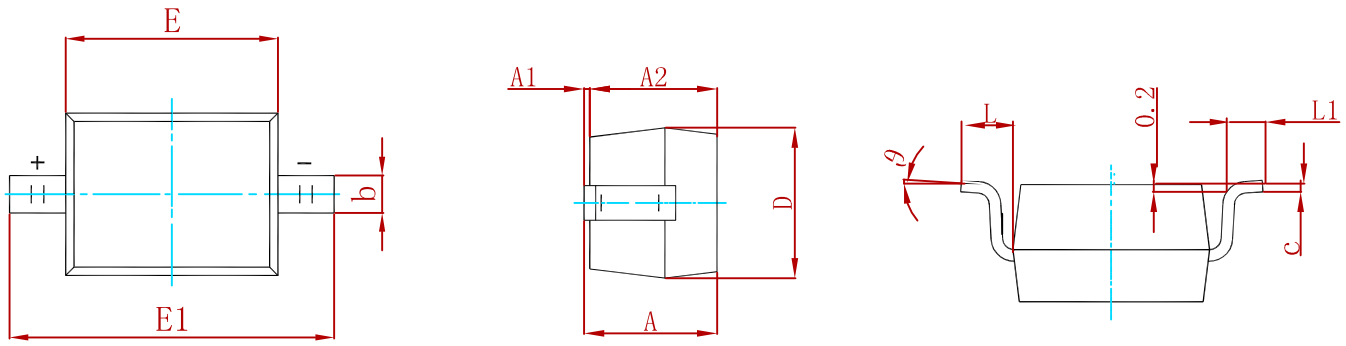
Capacitance Characteristics



Power Derating Curve

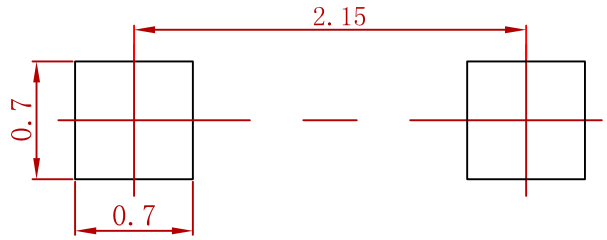


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAT54WS	SOD-323	3000

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